

**TOYO LED ELECTRONICS LIMITED** 

Room 1610, Hong Kong Plaza, 188 Connaught Road West, Hong Kong.Tel : (852) 2540 7288Fax : (852) 2517 1797http://www.toyo-led.comE-mail : sales@toyo-led.com



P/N: TY-YSV1204RGB1(1.50)-R5

3.2\* 1.0mm TOP SMD Series

# SPECIFICATION FOR CUSTOMER APPROVAL

## P/N:TY-YSV1204RGB1(1.50)-R5

PREPARED BY : STEVEN

CONFIRMED BY :

PLEASE CONFIRM & SIGN BACK THIS SHEET TO US

**CUSTOMER:** 

**APPROVAL BY:** 

(COMPANY CHOP)

(SIGNATURE)



♦

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#### Features:

- ➤ 3.2mm×1.0mm SMT LED> 1.50mm thickness
- PLCC-4 package
- ➢ White package
- > Suitable for all SMT assembly and solder process
- ➤ Available on 8mm tape and on 178mm reel

#### ♦ Description

The Red source color devices are made with AlGaInP on sapphire Light Emitting Diode.

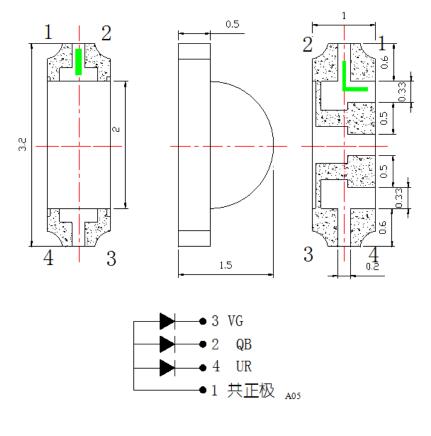
The Green source color devices are made with InGaN on Green Light Emitting Diode.

The Blue source color devices are made with InGaN on sapphire Light Emitting Diode.

#### ♦ Application

- Optical indicator
- Indicator and backlighting in telephone and fax
- Flat backlight for LCD, switch and symbol
- Light pipe application
- ➢ General use

#### ♦ Package Outline Dimensions



#### NOTES:

- 1. All dimensions are in millimeter;
- 2. Tolerance is±0.2mm unless other specified;
- 3. Specifications are subject to change without notice.





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TED

	Part No.	Lei	Len's Color			Chip Material				
	TY-YSV1204RGB1(1.50)-R5	Red	Green	Blue	Water clear			InGaN	InGaN	InGaN
	Absolute Maximum Ratings(Ta=25°C)									
$\diamond$	Absolute Maximum Ratings(T	[a=25℃)								
¢	Absolute Maximum Ratings(T	,			Syn	ıbol	Maxi	mum	Un	it
<b>~</b>		,			Syn	1 <b>bol</b> R		<b>mum</b> 5	Un	it
×		,			Syn PD	<b>F</b>	5		Un	

1				
		В	80	
Forward Current	In	R/B	25	
Forward Current	If	G	25	mA
Peak Forward Current(1/10 Duty Cycle 0.1ms Pulse	IFP	G/B	60	mA
Width)	IFP	В	60	mA
Reverse Voltage	V	Ŕ	5	V
Operating Temperature Range	Top	/ Tstg	-40 to+85	°C
Storage Temperature Range	Topr	Tstg	-40 to+85	°C

#### ♦ Electrical/Optical Characteristics(Ta=25°C)

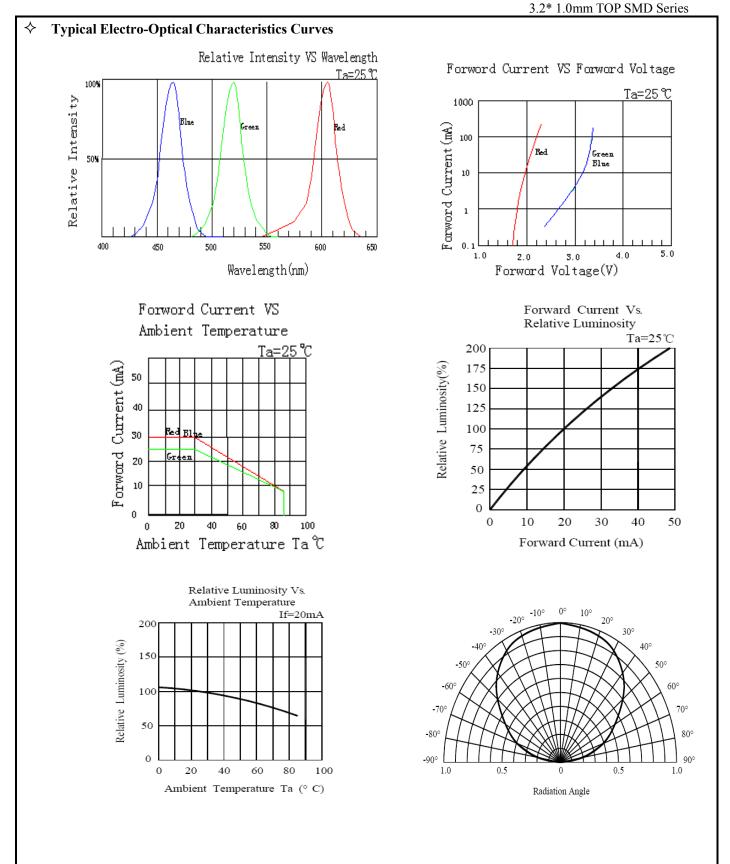
Item	Symbol		Condition	Min.	Тур.	Max	Unit
Forward Voltage	VF	R	IF=20mA	1.7	2.0	2.4	V
rorward voltage	V F	G/B	IF-20IIIA	2.8	3.0	3.4	v
		R		100	200		
Luminous Intensity	Iv	G	IF=20mA	350	550		mcd
		В		100	200		
		R		617		630	
Wavelength	λ	G	IF=20mA	515		530	nm
		В		460		475	
Viewing Angle	26	1/2	IF=20mA		120		deg
Reverse Current	]	R	$V_R = 5V$		5	10	uA

NOTES:

- 1. Tolerance is  $\pm 0.25$ mm unless other specified;
- 2. Luminous intensity testing tolerance is  $\pm 10\%$ ;
- 3. Dominant Emission Wavelength testing tolerance is  $\pm 5\%$ ;
- 4. Specifications are subject to change without notice.











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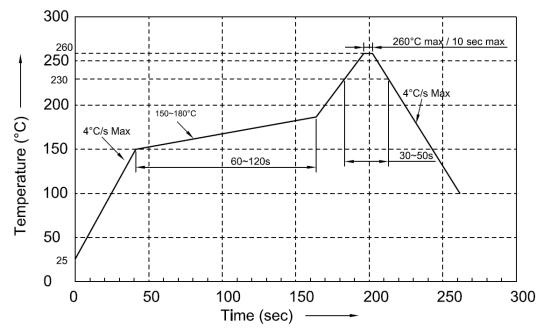


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≻ Reliab	liability Test Items And Conditions								
ח	NO.	Item	Test Condition	Test Hr/cycle/time	Sample Qty	Ac/Re			
	1	Reflow	TEMP:260±5℃; (3-7 sec)	6 min	22pcs	0/1			
	2	High Temperature /Humidity Storage	TEMP: 85°C/ R.H.:85%	1000hrs	22pcs	0/1			
	3	Low Temperature Storage	ТЕМР: -40°С	1000hrs	22pcs	0/1			
	4	DC Operating Life	IF=20mA	1000hrs	22pcs	0/1			

#### ♦ Recommended SMT Reflow Soldering Instructions

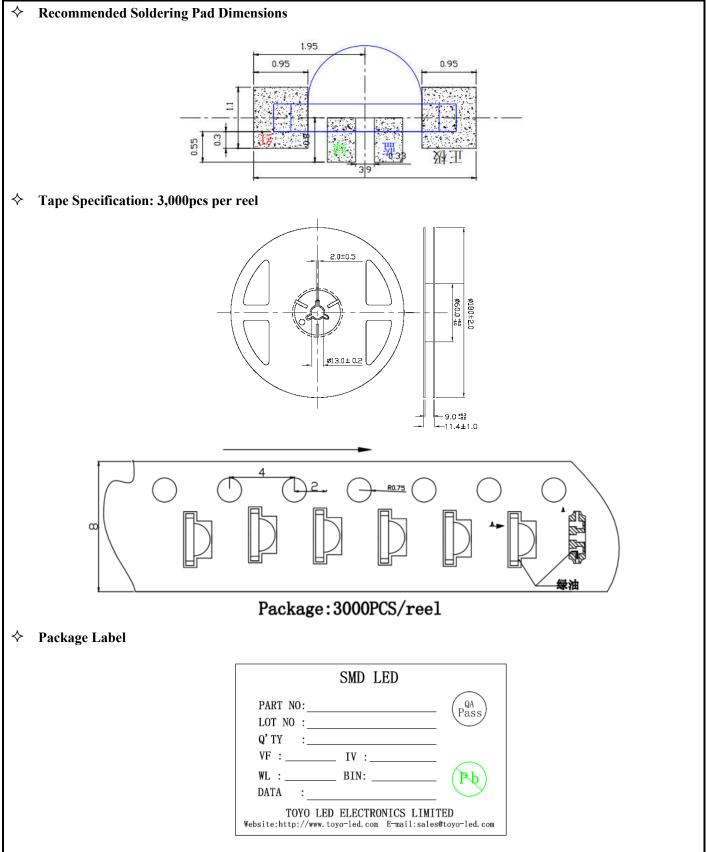


Notes:

- 1. We recommend the reflow temperature 245±5°C. The maximum soldering temperature should be limited to 260°C for 10s (max).
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

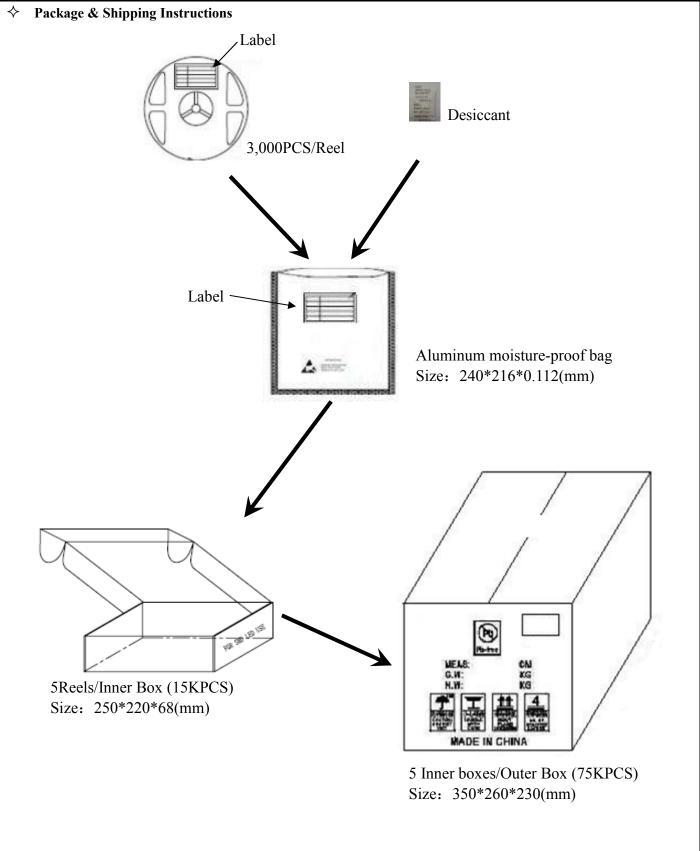












#### Sample Number:

A,

B′

∻

∻

Storage

unpacking the sealed envelope.

process must be:

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Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is

recommended when handing these LED. All devices, equipment and machinery must be properly grounded.

In order to prevent the absorption of moisture, it is recommended to solder TOYO LEDs as soon as possible after

2 After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering

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#### ∻ **Handling Precautions**

#### Epoxy resin is hard & brittle and silicone is softer & flexible. Although its characteristic significantly thermal stress, it is more susceptible to damage by external mechanical force.

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As a result, special handling precautions need to be observed during assembly using silicone encapsulated

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LED products. Failure to comply might lead to damage and premature failure of the LED.

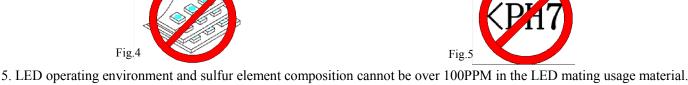
Fig 2

- 1. Handle the component along the side surface by using forceps or appropriate tools (fig.1); do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry(fig.2&3).
- The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent 2. air leaks. The inner diameter of the nozzle should be as large as possible. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.
- 3. Prevent stack together assembled PCBs containing. PH<7. LEDs. Impact may scratch the silicone lens or damage the internal circuitry(fig.4).

Fig.1

4. Non-suitable to operate in acidic environment, (Fig.5)





If the envelope is still packed, to store it in the environment as following:

③ Devices required baking before mounting, if:(2)a or (2)b is not met.

④ If baking is required, devices must be baked under below condition:48 hour at  $60^{\circ}C \pm 3^{\circ}C$ .

① Temperature:  $5^{\circ}$ C -  $30^{\circ}$ C ( $41^{\circ}$ F -  $86^{\circ}$ F) Humidity: RH 60% Max.

Completed within 168 hours.

Stored at less than 30% RH.

ESD (Electrostatic Discharge)







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#### ♦ Other

- 1. Above specification may be changed without notice. TOYO will reserve authority on material change for above specification.
- 2. When using this product, please abserve the absolute maximum ratings and the instructions for using outlined in these specification sheets. TOYO assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.

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DATE	REVISION CONTENTS	VERSION
2021-10-07	New	А

**REVISION HISTORY**